

74HC240; 74HCT240

Octal buffer/line driver; 3-state; inverting

Rev. 4 — 25 February 2016

Product data sheet

1. General description

The 74HC240; 74HCT240 is an 8-bit inverting buffer/line driver with 3-state outputs. The device can be used as two 4-bit buffers or one 8-bit buffer. The device features two output enables ($1\overline{OE}$ and $2\overline{OE}$), each controlling four of the 3-state outputs. A HIGH on $n\overline{OE}$ causes the outputs to assume a high-impedance OFF-state. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of V_{CC} .

2. Features and benefits

- Complies with JEDEC standard JESD7A
- Input levels:
 - ◆ For 74HC240: CMOS level
 - ◆ For 74HCT240: TTL level
- Inverting 3-state outputs
- ESD protection:
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ and from $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$

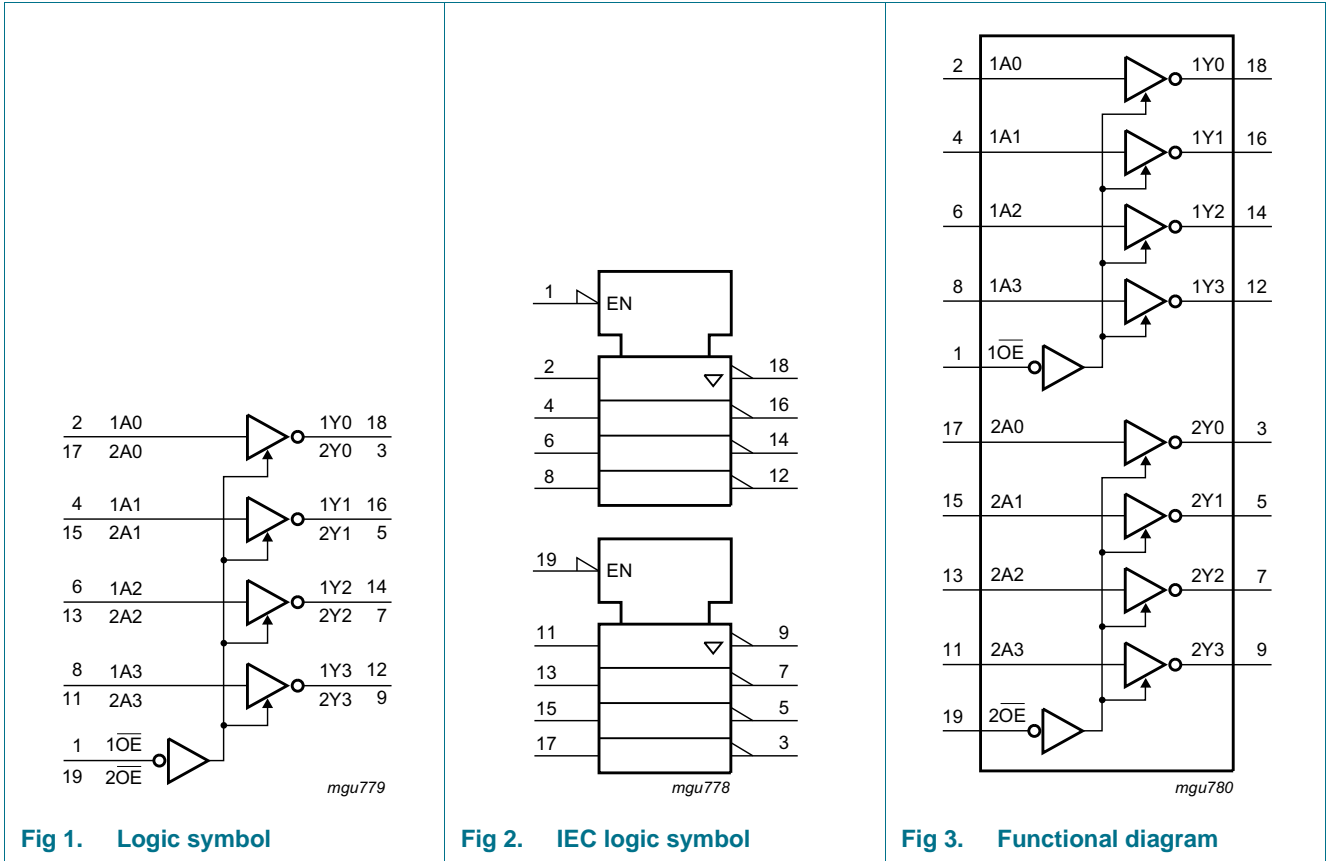
3. Ordering information

Table 1. Ordering information

| Type number | Package | | | |
|-------------|-------------------|----------|---|----------|
| | Temperature range | Name | Description | Version |
| 74HC240D | -40 °C to +125 °C | SO20 | plastic small outline package; 20 leads; body width 7.5 mm | SOT163-1 |
| 74HCT240D | | | | |
| 74HC240DB | -40 °C to +125 °C | SSOP20 | plastic shrink small outline package; 20 leads; body width 5.3 mm | SOT339-1 |
| 74HCT240DB | | | | |
| 74HC240PW | -40 °C to +125 °C | TSSOP20 | plastic thin shrink small outline package; 20 leads; body width 4.4 mm | SOT360-1 |
| 74HCT240PW | | | | |
| 74HC240BQ | -40 °C to +125 °C | DHVQFN20 | plastic dual-in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body $2.5 \times 4.5 \times 0.85\text{ mm}$ | SOT764-1 |
| 74HCT240BQ | | | | |



4. Functional diagram



5. Pinning information

5.1 Pinning

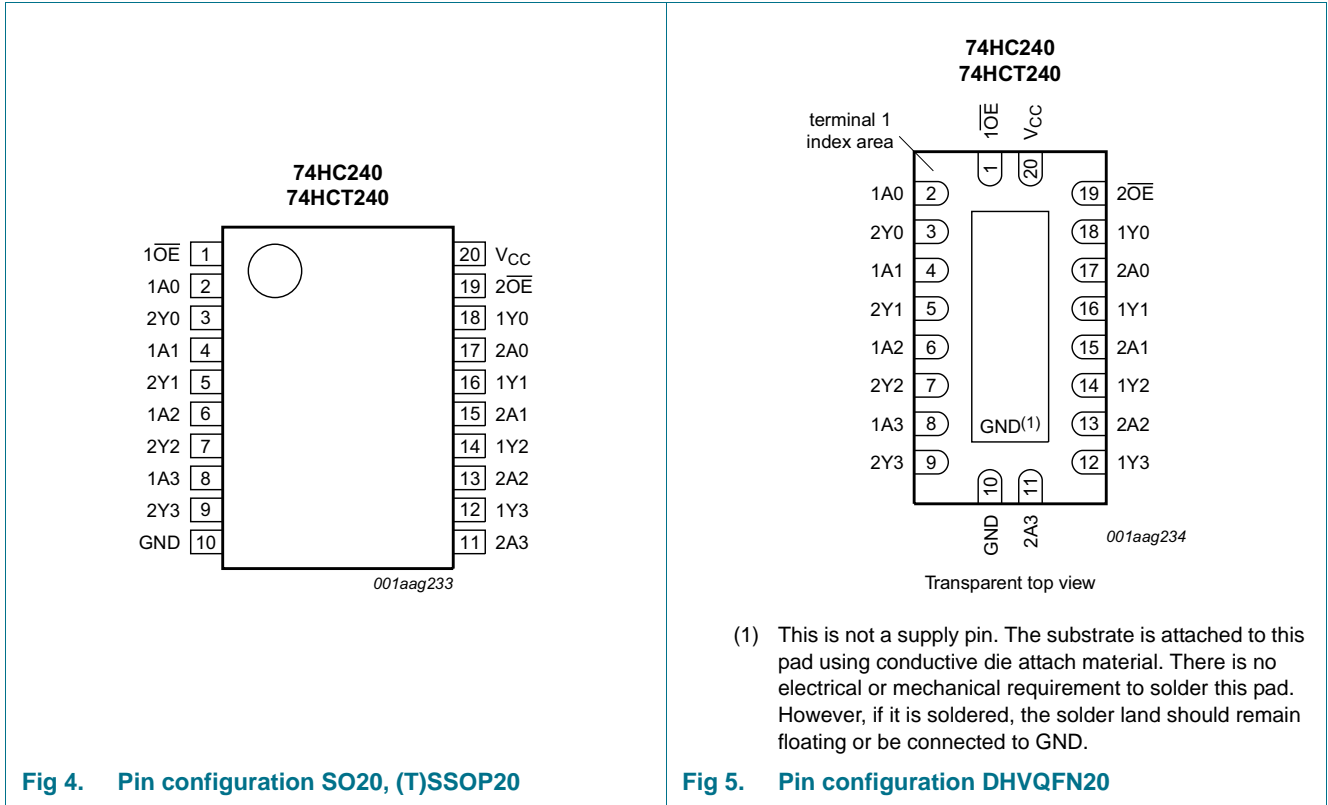


Fig 4. Pin configuration SO20, (T)SSOP20

Fig 5. Pin configuration DHVQFN20

5.2 Pin description

Table 2. Pin description

| Symbol | Pin | Description |
|--------------------|----------------|----------------------------------|
| 10E, 20E | 1, 19 | output enable input (active LOW) |
| 1A0, 1A1, 1A2, 1A3 | 2, 4, 6, 8 | data input |
| 2Y0, 2Y1, 2Y2, 2Y3 | 3, 5, 7, 9 | bus output |
| GND | 10 | ground (0 V) |
| 2A0, 2A1, 2A2, 2A3 | 17, 15, 13, 11 | data input |
| 1Y0, 1Y1, 1Y2, 1Y3 | 18, 16, 14, 12 | bus output |
| V _{CC} | 20 | supply voltage |

6. Functional description

Table 3. Function table^[1]

| Input | | Output |
|-------|-----|--------|
| nOE | nAn | nYn |
| L | L | H |
| L | H | L |
| H | X | Z |

- [1] H = HIGH voltage level;
 L = LOW voltage level;
 X = don't care;
 Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|------------------|-------------------------|---|------|------|------|
| V _{CC} | supply voltage | | -0.5 | +7 | V |
| I _{IK} | input clamping current | V _I < -0.5 V or V _I > V _{CC} + 0.5 V | - | ±20 | mA |
| I _{OK} | output clamping current | V _O < -0.5 V or V _O > V _{CC} + 0.5 V | - | ±20 | mA |
| I _O | output current | -0.5 V < V _O < V _{CC} + 0.5 V | - | ±35 | mA |
| I _{CC} | supply current | | - | 70 | mA |
| I _{GND} | ground current | | -70 | - | mA |
| T _{stg} | storage temperature | | -65 | +150 | °C |
| P _{tot} | total power dissipation | SO20, SSOP20, TSSOP20 and DHVQFN20 packages ^[1] | - | 500 | mW |

- [1] For SO20 packages: above 70 °C, P_{tot} derates linearly with 8 mW/K.
 For SSOP20 and TSSOP20 packages: above 60 °C, P_{tot} derates linearly with 5.5 mW/K.
 For DHVQFN20 packages: above 60 °C, P_{tot} derates linearly with 4.5 mW/K.

8. Recommended operating conditions

Table 5. Recommended operating conditions

| Symbol | Parameter | Conditions | 74HC240 | | | 74HCT240 | | | Unit |
|------------------|-------------------------------------|-------------------------|---------|------|-----------------|----------|------|-----------------|------|
| | | | Min | Typ | Max | Min | Typ | Max | |
| V _{CC} | supply voltage | | 2.0 | 5.0 | 6.0 | 4.5 | 5.0 | 5.5 | V |
| V _I | input voltage | | 0 | - | V _{CC} | 0 | - | V _{CC} | V |
| V _O | output voltage | | 0 | - | V _{CC} | 0 | - | V _{CC} | V |
| Δt/ΔV | input transition rise and fall rate | V _{CC} = 2.0 V | - | - | 625 | - | - | - | ns/V |
| | | V _{CC} = 4.5 V | - | 1.67 | 139 | - | 1.67 | 139 | ns/V |
| | | V _{CC} = 6.0 V | - | - | 83 | - | - | - | ns/V |
| T _{amb} | ambient temperature | | -40 | +25 | +125 | -40 | +25 | +125 | °C |

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +85 °C | | -40 °C to +125 °C | | Unit |
|-----------------|---------------------------|--|-------|------|------|------------------|------|-------------------|------|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| 74HC240 | | | | | | | | | | |
| V _{IH} | HIGH-level input voltage | V _{CC} = 2.0 V | 1.5 | 1.2 | - | 1.5 | - | 1.5 | - | V |
| | | V _{CC} = 4.5 V | 3.15 | 2.4 | - | 3.15 | - | 3.15 | - | V |
| | | V _{CC} = 6.0 V | 4.2 | 3.2 | - | 4.2 | - | 4.2 | - | V |
| V _{IL} | LOW-level input voltage | V _{CC} = 2.0 V | - | 0.8 | 0.5 | - | 0.5 | - | 0.5 | V |
| | | V _{CC} = 4.5 V | - | 2.1 | 1.35 | - | 1.35 | - | 1.35 | V |
| | | V _{CC} = 6.0 V | - | 2.8 | 1.8 | - | 1.8 | - | 1.8 | V |
| V _{OH} | HIGH-level output voltage | V _I = V _{IH} or V _{IL} | | | | | | | | |
| | | I _O = -20 μA; V _{CC} = 2.0 V | 1.9 | 2.0 | - | 1.9 | - | 1.9 | - | V |
| | | I _O = -20 μA; V _{CC} = 4.5 V | 4.4 | 4.5 | - | 4.4 | - | 4.4 | - | V |
| | | I _O = -20 μA; V _{CC} = 6.0 V | 5.9 | 6.0 | - | 5.9 | - | 5.9 | - | V |
| | | I _O = -6.0 mA; V _{CC} = 4.5 V | 3.98 | 4.32 | - | 3.84 | - | 3.7 | - | V |
| V _{OL} | LOW-level output voltage | V _I = V _{IH} or V _{IL} | | | | | | | | |
| | | I _O = 20 μA; V _{CC} = 2.0 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 20 μA; V _{CC} = 4.5 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 20 μA; V _{CC} = 6.0 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 6.0 mA; V _{CC} = 4.5 V | - | 0.15 | 0.26 | - | 0.33 | - | 0.4 | V |
| | | I _O = 7.8 mA; V _{CC} = 6.0 V | - | 0.16 | 0.26 | - | 0.33 | - | 0.4 | V |
| | | | | | | | | | | |
| I _I | input leakage current | V _I = V _{CC} or GND; V _{CC} = 6.0 V | - | - | ±0.1 | - | ±1.0 | - | ±1.0 | μA |
| I _{OZ} | OFF-state output current | V _I = V _{IH} or V _{IL} ; V _{CC} = 6.0 V; V _O = V _{CC} or GND | - | - | ±0.5 | - | ±5.0 | - | ±10 | μA |
| I _{CC} | supply current | V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 6.0 V | - | - | 8.0 | - | 80 | - | 160 | μA |
| C _I | input capacitance | | - | 3.5 | - | - | - | - | - | pF |
| 74HCT240 | | | | | | | | | | |
| V _{IH} | HIGH-level input voltage | V _{CC} = 4.5 V to 5.5 V | 2.0 | 1.6 | - | 2.0 | - | 2.0 | - | V |
| V _{IL} | LOW-level input voltage | V _{CC} = 4.5 V to 5.5 V | - | 1.2 | 0.8 | - | 0.8 | - | 0.8 | V |
| V _{OH} | HIGH-level output voltage | V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V | | | | | | | | |
| | | I _O = -20 μA | 4.4 | 4.5 | - | 4.4 | - | 4.4 | - | V |
| | | I _O = -6 mA | 3.98 | 4.32 | - | 3.84 | - | 3.7 | - | V |
| V _{OL} | LOW-level output voltage | V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V | | | | | | | | |
| | | I _O = 20 μA | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 6.0 mA | - | 0.16 | 0.26 | - | 0.33 | - | 0.4 | V |

Table 6. Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +85 °C | | -40 °C to +125 °C | | Unit |
|------------------|---------------------------|---|-------|-----|------|------------------|------|-------------------|------|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| I _I | input leakage current | V _I = V _{CC} or GND; V _{CC} = 5.5 V | - | - | ±0.1 | - | ±1.0 | - | ±1.0 | µA |
| I _{OZ} | OFF-state output current | V _I = V _{IH} or V _{IL} ; V _{CC} = 5.5 V; V _O = V _{CC} or GND | - | - | ±0.5 | - | ±5.0 | - | ±10 | µA |
| I _{CC} | supply current | V _I = V _{CC} or GND; V _{CC} = 5.5 V; I _O = 0 A | - | - | 8.0 | - | 80 | - | 160 | µA |
| ΔI _{CC} | additional supply current | per input pin; V _I = V _{CC} - 2.1 V; other inputs at V _{CC} or GND; V _{CC} = 4.5 V to 5.5 V; I _O = 0 A | | | | | | | | |
| | | nAn or inputs | - | 150 | 540 | - | 675 | - | 735 | µA |
| | | nOE input | - | 70 | 252 | - | 315 | - | 343 | µA |
| C _I | input capacitance | | - | 3.5 | - | - | - | - | - | pF |

10. Dynamic characteristics

Table 7. Dynamic characteristics

GND = 0 V; for test circuit see [Figure 8](#).

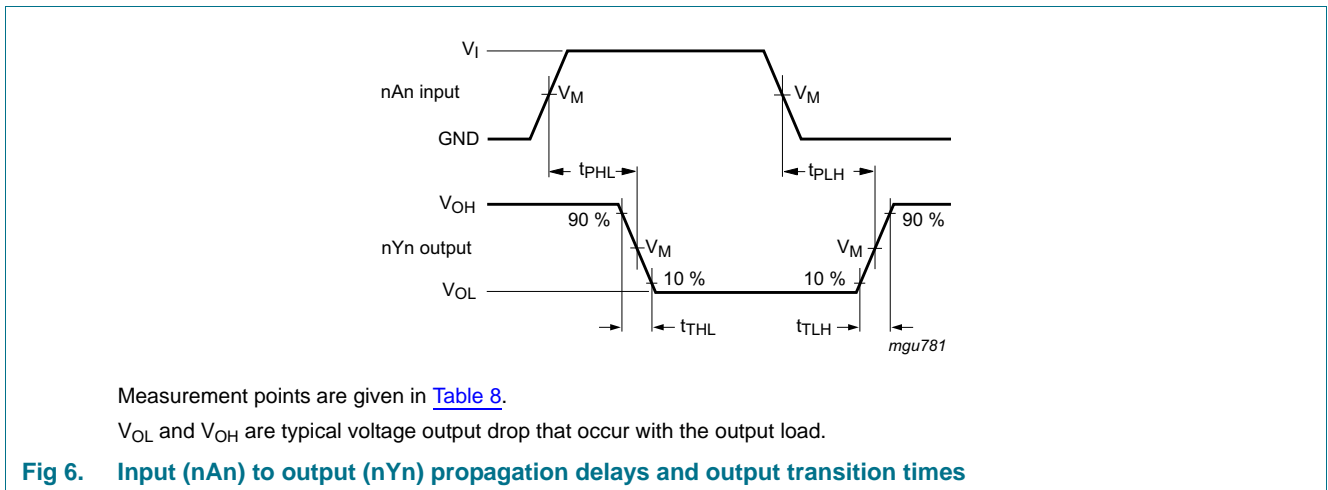
| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +125 °C | | Unit |
|------------------|-------------------|---|-------|-----|-----|-------------------|--------------|------|
| | | | Min | Typ | Max | Max (85 °C) | Max (125 °C) | |
| 74HC240 | | | | | | | | |
| t _{pd} | propagation delay | nAn to nYn; see Figure 6 [1] | | | | | | |
| | | V _{CC} = 2.0 V | - | 30 | 100 | 125 | 150 | ns |
| | | V _{CC} = 4.5 V | - | 11 | 20 | 25 | 30 | ns |
| | | V _{CC} = 5.0 V; C _L = 15 pF | - | 9 | - | - | - | ns |
| | | V _{CC} = 6.0 V | - | 9 | 17 | 21 | 26 | ns |
| t _{en} | enable time | nOE to nYn; see Figure 7 [2] | | | | | | |
| | | V _{CC} = 2.0 V | - | 39 | 150 | 190 | 225 | ns |
| | | V _{CC} = 4.5 V | - | 14 | 30 | 38 | 45 | ns |
| | | V _{CC} = 6.0 V | - | 11 | 26 | 33 | 38 | ns |
| t _{dis} | disable time | nOE to nYn or see Figure 7 [3] | | | | | | |
| | | V _{CC} = 2.0 V | - | 41 | 150 | 190 | 225 | ns |
| | | V _{CC} = 4.5 V | - | 15 | 30 | 38 | 45 | ns |
| | | V _{CC} = 6.0 V | - | 12 | 26 | 33 | 38 | ns |
| t _t | transition time | see Figure 6 [4] | | | | | | |
| | | V _{CC} = 2.0 V | - | 14 | 60 | 75 | 90 | ns |
| | | V _{CC} = 4.5 V | - | 5 | 12 | 15 | 18 | ns |
| | | V _{CC} = 6.0 V | - | 4 | 10 | 13 | 15 | ns |

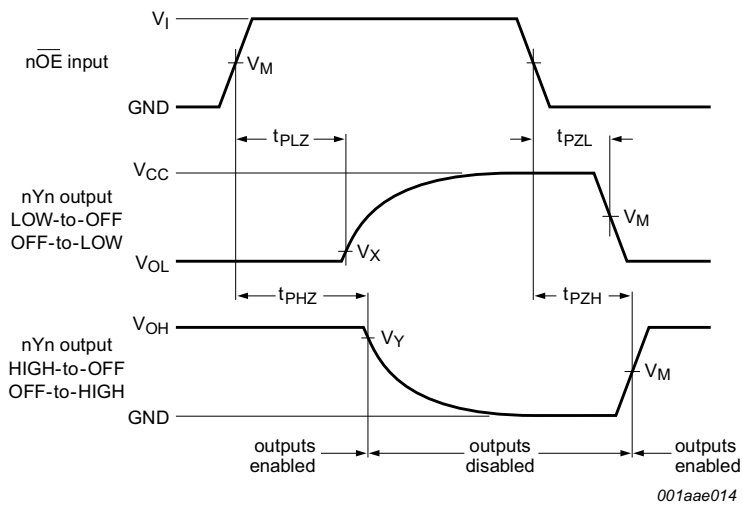
Table 7. Dynamic characteristics ...continued
GND = 0 V; for test circuit see Figure 8.

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +125 °C | | Unit |
|------------------|-------------------------------|--|-------|-----|-----|-------------------|--------------|------|
| | | | Min | Typ | Max | Max (85 °C) | Max (125 °C) | |
| C _{PD} | power dissipation capacitance | per transceiver; V _I = GND to V _{CC} [5] | - | 30 | - | - | - | pF |
| 74HCT240 | | | | | | | | |
| t _{pd} | propagation delay | nAn to nYn; see Figure 6 [1] | | | | | | |
| | | V _{CC} = 4.5 V | - | 11 | 20 | 25 | 30 | ns |
| | | V _{CC} = 5.0 V; C _L = 15 pF | - | 9 | - | - | - | ns |
| t _{en} | enable time | nOE to nYn; V _{CC} = 4.5 V; see Figure 7 [2] | - | 13 | 30 | 38 | 45 | ns |
| t _{dis} | disable time | nOE to nYn; V _{CC} = 4.5 V; see Figure 7 [3] | - | 13 | 25 | 31 | 38 | ns |
| t _t | transition time | V _{CC} = 4.5 V; see Figure 6 [4] | - | 5 | 12 | 15 | 18 | ns |
| C _{PD} | power dissipation capacitance | per transceiver; V _I = GND to V _{CC} - 1.5 V [5] | - | 30 | - | - | - | pF |

- [1] t_{pd} is the same as t_{PHL} and t_{PLH}.
- [2] t_{en} is the same as t_{PZH} and t_{PZL}.
- [3] t_{dis} is the same as t_{PHZ} and t_{PLZ}.
- [4] t_t is the same as t_{THL} and t_{TLH}.
- [5] C_{PD} is used to determine the dynamic power dissipation (P_D in μW):
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum (C_L \times V_{CC}^2 \times f_o)$ where:
 f_i = input frequency in MHz;
 f_o = output frequency in MHz;
 C_L = output load capacitance in pF;
 V_{CC} = supply voltage in V;
 N = number of inputs switching;
 $\sum (C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.

11. Waveforms





Measurement points are given in [Table 8](#).

V_{OL} and V_{OH} are typical voltage output drop that occur with the output load.

Fig 7. 3-state enable and disable times

Table 8. Measurement points

| Type | Input | Output | | |
|----------|---------------------|---------------------|---------------------|---------------------|
| | V_M | V_M | V_X | V_Y |
| 74HC240 | $0.5 \times V_{CC}$ | $0.5 \times V_{CC}$ | $0.1 \times V_{CC}$ | $0.9 \times V_{CC}$ |
| 74HCT240 | 1.3 V | 1.3 V | $0.1 \times V_{CC}$ | $0.9 \times V_{CC}$ |

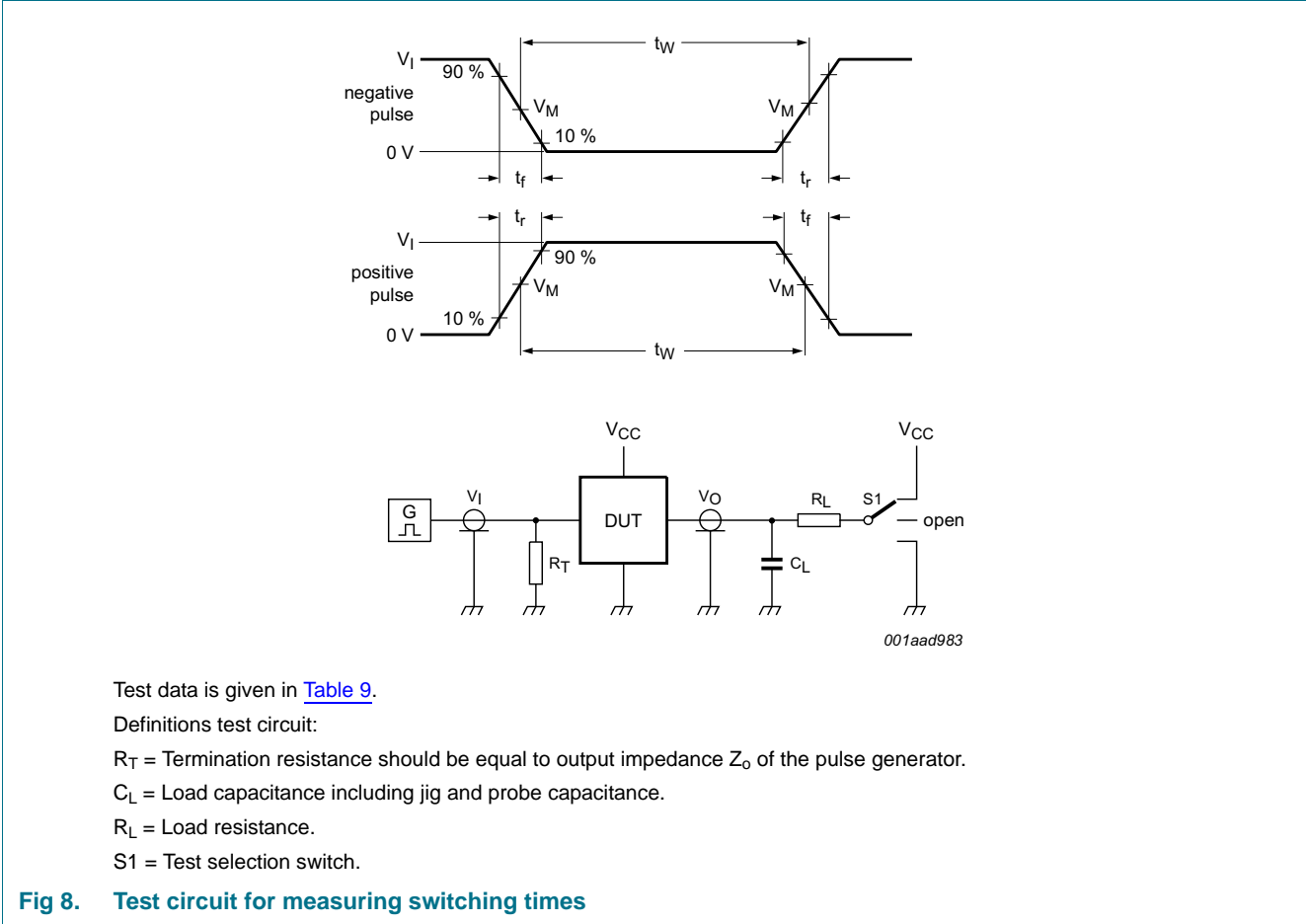


Table 9. Test data

| Type | Input | | Load | | S1 position | | |
|----------|----------|------------|--------------|--------------|--------------------|--------------------|--------------------|
| | V_I | t_r, t_f | C_L | R_L | t_{PHL}, t_{PLH} | t_{PZH}, t_{PHZ} | t_{PZL}, t_{PLZ} |
| 74HC240 | V_{CC} | 6 ns | 15 pF, 50 pF | 1 k Ω | open | GND | V_{CC} |
| 74HCT240 | 3 V | 6 ns | 15 pF, 50 pF | 1 k Ω | open | GND | V_{CC} |

12. Package outline

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1

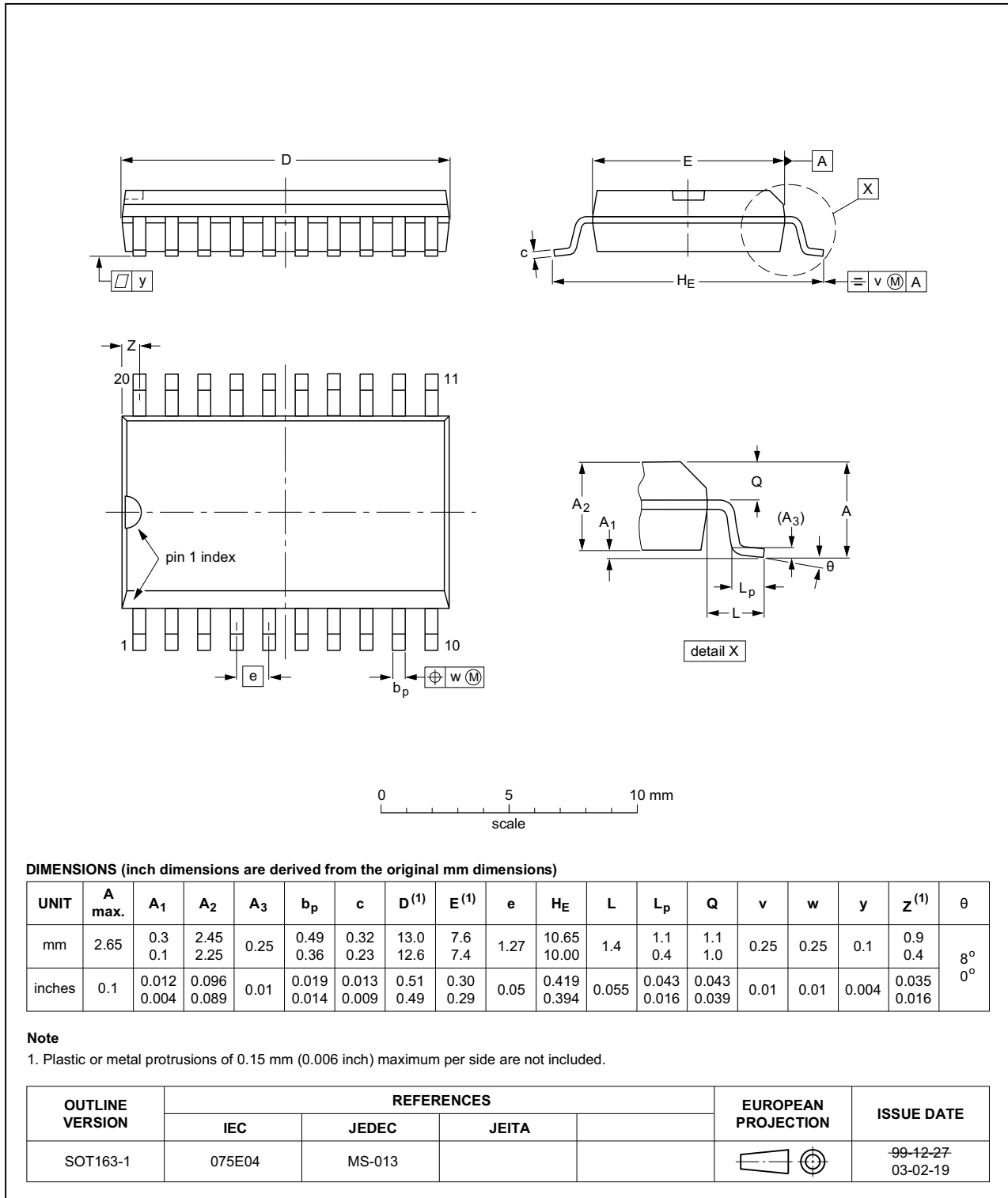


Fig 9. Package outline SOT163-1 (SO20)

SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1

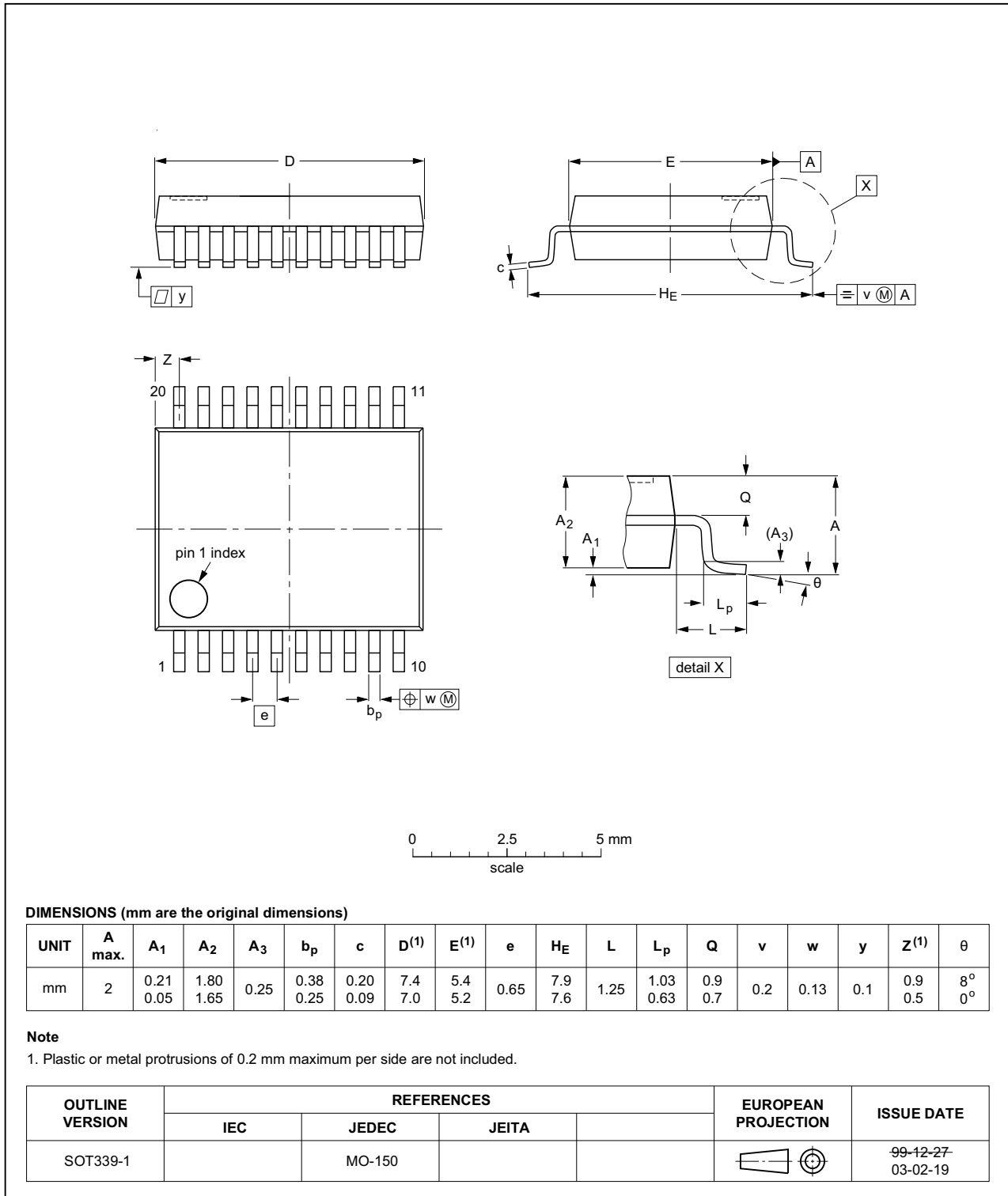


Fig 10. Package outline SOT339-1 (SSOP20)

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1

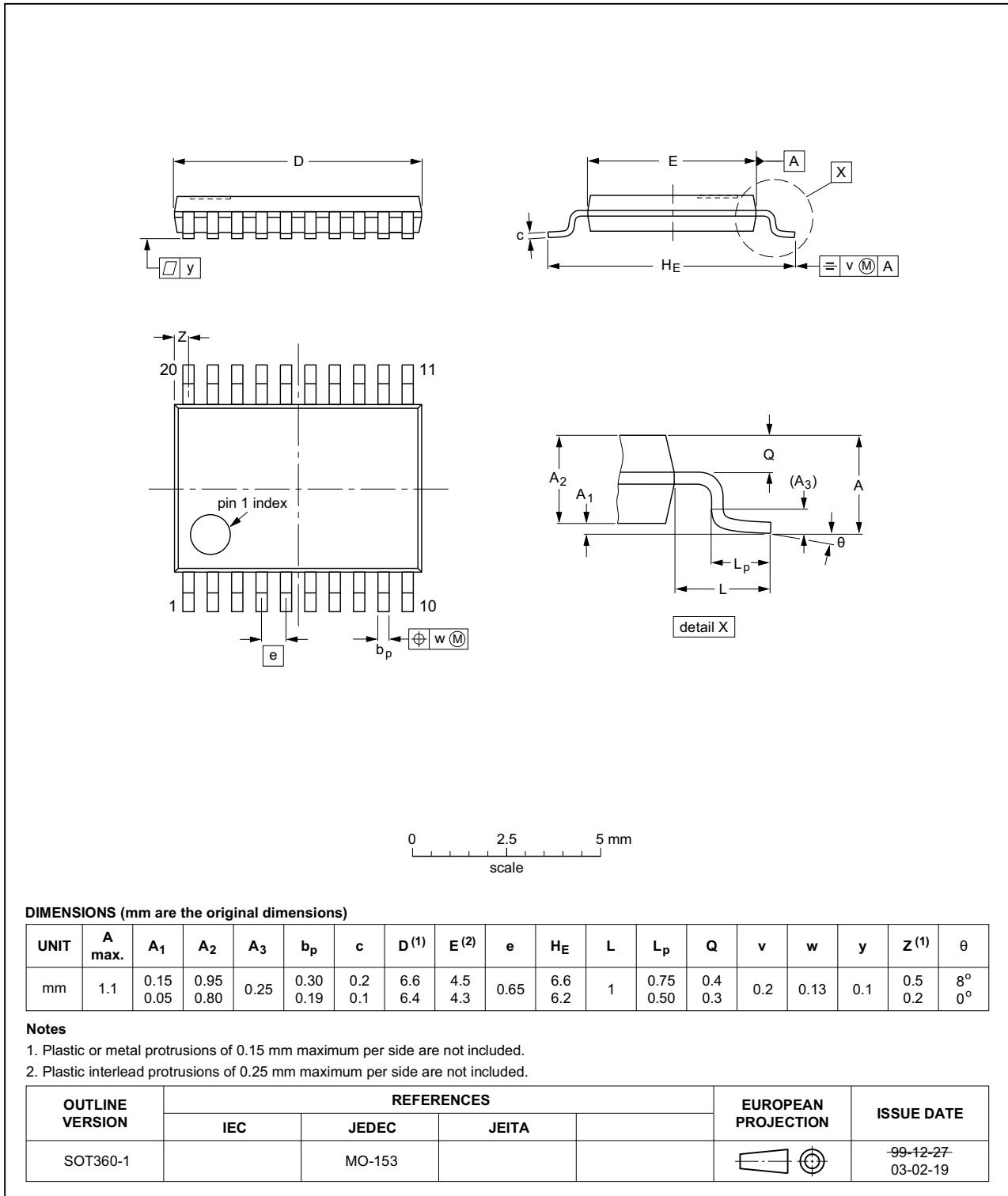


Fig 11. Package outline SOT360-1 (TSSOP20)

DHVQFN20: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 x 4.5 x 0.85 mm

SOT764-1

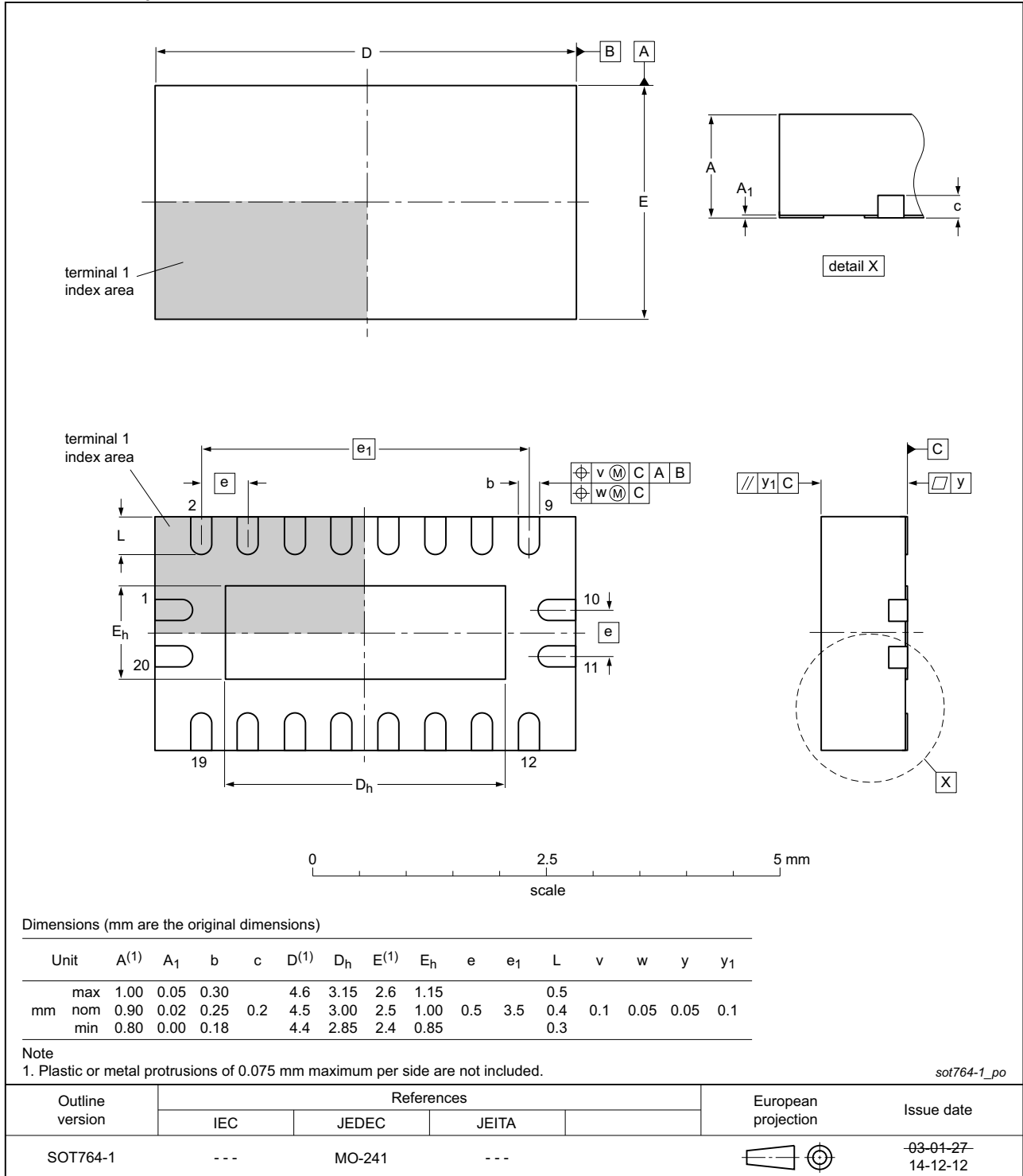


Fig 12. Package outline SOT764-1 (DHVQFN20)

13. Abbreviations

Table 10. Abbreviations

| Acronym | Description |
|---------|---|
| CMOS | Complementary Metal Oxide Semiconductor |
| DUT | Device Under Test |
| ESD | ElectroStatic Discharge |
| HBM | Human Body Model |
| MM | Machine Model |
| TTL | Transistor-Transistor Logic |

14. Revision history

Table 11. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|---------------------|--|-----------------------|---------------|---------------------|
| 74HC_HCT240 v.4 | 20160225 | Product data sheet | - | 74HC_HCT240 v.3 |
| Modifications: | <ul style="list-style-type: none"> Type numbers 74HC240N and 74HCT240N (SOT146-1) removed. | | | |
| 74HC_HCT240 v.3 | 20070802 | Product data sheet | - | 74HC_HCT240_CNV v.2 |
| Modifications: | <ul style="list-style-type: none"> The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. Legal texts have been adapted to the new company name where appropriate. Added type number 74HC240BQ and 74HCT240BQ (DHVQFN20 package) | | | |
| 74HC_HCT240_CNV v.2 | 19970828 | Product specification | - | - |

15. Legal information

15.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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